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The Leading International Components, Packaging and Manufacturing Technology Symposium



November 13-15, 2024

Ritsumeikan University's Suzaku Campus, Kyoto, Japan



Advanced Program (Last update: September 20, 2024)

November 13, 2024 (Wednesday)

4F/5F Main Hall I		1F Room I Registration	1F Room II
9:00			
10:10	Opening Remark (General Chair, Eiji Higurashi)		
10:25	Guest speech TBD (President of Ritsumeikan University, Yoshio Nakatani)		
10:35	Award Ceremony		
10:50-12:30	Plenary Speech I & II Hall I Chairperson TBD		
10:50	Plenary Speech I: Silicon Photonic MEMS Switch for AI Super Computers Ming Wu (University of California, Berkley)		P-02
11:40	Plenary Speech II: Silicon Photonics Light Engines with 2.5/3D Heterogeneous Integration Radhakrishnan Nagarajan (Marvell Technology)		P-03
12:35-12:50		Platinum Sponsors' Seminar 1 (with a light meal) @Meeting Room 1	
12:50-13:05		Platinum Sponsors' Seminar 2 (with a light meal) @Meeting Room 1	
12:05-13:20		Platinum Sponsors' Seminar 3 (with a light meal) @Meeting Room 1	
13:30-15:25	Session 1: Photonics I (Active Optical Device) Chairperson Nobuo Ohata (Mitsubishi Electric Corporation) Motohito Takezaki (Hakusan Inc.)	Session 2: Process and Material Technologies I Chairperson Satomi Kawamoto (NAMICS Corporation) Kei Murayama (Shinko Electric Industries Co., Ltd.)	Session 3: High-Speed Package and System Chairperson Kazuyuki Nakagawa (Renesas Electronics Corporation) Ryo Sakamaki (AIST)
13:30	3.2T Co-Package Optics (CPO) Module Based on 200G/ch Silicon-Organic-Hybrid (SOH) <i>Chin-Ta Chen, Kao-Feng Tsai</i> <i>Centera Photonics Inc.</i>	01-01 Fluxless Low-Temperature Flip Chip Solder Interconnect for Cost Reduction. <i>Teck Kheng Lee Teck Kheng Lee, Kelvin Zheng Kelvin Zheng, Kyu Sik Shim Kyu Sik Shim</i> <i>Institute of Technical Education</i>	02-01 (Invited) TBD
13:55	01-02 An Ultra-Compact 106-Gb/s PAM4 x 8-Channel Linear-Drive VCSEL-Based Transceiver for Co-Packaged Optics <i>Wataru Yoshida, Kazuya Nagashima, Kensho Nishizaki, Hideyuki Nasu</i> <i>Furukawa Electric Co., Ltd.</i>	02-02 AI wiring and Cu wiring connection by newly established AL-ribbon stack bonding technology for Power package and module <i>Noriko Numata, Takashi Aoki, Koichi Hasegawa, Manabu Nejiki, Ken Yamamura, Kazuyuki Nakagawa</i> <i>Renesas Electronics Corporation</i>	03-02 High Density, High Bandwidth Copper Interconnects to Support High Density IC Packaging <i>Kevin Burt, Steve Krooswyk, Andy Shrout, Jignesh Shah, Akinori Mizumura, Chad Faith</i> <i>Samtec, Inc</i>
14:20	01-03 Over 25-GHz Bandwidth Testing Station using a 0.3-mm-Pitch LGA Interface for a 50-Gbaud x 16-channel CPO Transceiver <i>Kensho Nishizaki, Kazuya Nagashima, Wataru Yoshida, Hideyuki Nasu</i> <i>Furukawa Electric Co., Ltd.</i>	02-03 Enhancing Adhesion and Peel strength for fine line design on FCCSP Package <i>Rick Yeh, MJ HE, Yu-Cheng Pai, Carl Chen, Yu-Po Wang</i> <i>SPIL</i>	03-03 A Study on Reducing Crosstalk by Efficiently Placing Guard Vias <i>Msasahiro Yao, Norio Chujo</i> <i>Hitachi, Ltd.</i>
14:45	01-04 Design of Thin-film Narrowband Retroreflector for Oblique Incidence of Diverging Wave <i>Keisuke Sakatani, Yuya Yamanishi, Keisuke Ozawa, Junichi Inoue, Shogo Ura</i> <i>Kyoto Institute of Technology</i>	02-04 Comparative studies on the reliability and intermetallic integrity of novel Au-coated Ag versus Cu and Au bonding wires <i>Randolph Flauta, Jorex Lumanog, Suqin Huang, Joe Zhou, King Man Tai, Moon Chen</i> <i>Nexperia Group</i>	03-04 Signal Integrity Analysis and Design for HBM3 on Silicon-Based 2.5D Packaging <i>Li-Chieh Hung, Cheng-Yu Tsai, Hung-Chun Kuo, Ming-Fong Jhong, Chen-Chao Wang</i> <i>ASE</i>
15:10	Interview with the Authors (Discussion after the session) + Sponsor's Exhibition		
15:25	Coffee break + Sponsor's Exhibition		
15:40-17:35	Session 4: Photonics II (Optical Fiber and Connector) Chairperson Hidetoshi Numata (IBM Research - Tokyo) Junichi Inoue (Kyoto Institute of Technology)	Session 5: Process and Material Technologies II Chairperson Satomi Kawamoto (NAMICS Corporation) Naoko Araki (DAICEL CORPORATION)	Session 6: mmWave AiP EMC Package and Systems Chairperson Yoichiro Kurita (Tokyo Institute of Technology) Wataru Shiroy (Renesas Electronics Corporation)
15:40	04-01 Bend-optimized Optical Fiber with Low Multi-path Interference in the O-band <i>Scott Bickham, Riley Freeland, Garth Scannell, Stephen Smith, Snigdharaj Mishra, Martin Hempstead, Madison Shipman</i> <i>Corning Research and Development Corporation</i>	05-01 (Invited) Thermally Stable Dry-Film Solder Resist for High Temperature Applications <i>Daisuke Shibata</i> <i>Taiyo Ink Mfg. Co. Ltd.</i>	06-01 Heat Dissipation Study of Sub-THz Band AiP Module <i>Makoto Tsukahara¹, Kei Murayama¹, Hiroko Ota¹, Hiroshi Taneda¹, Yoichi Nakagawa²</i> <i>1) Shinko Electric Industries Co., Ltd.</i> <i>2) Panasonic Industry Co., Ltd.</i>
16:05	04-02 Evaluation of MPI suppression by bending a short PMF cable attached to an ELS module <i>Noe Ishizuka, Daiki Takeda, Tsunetoshi Saito, Hideyuki Nasu</i> <i>Furukawa Electric Co., Ltd</i>	05-02 Five sided protection of the chip with Bump support film impact resistance <i>Reina Kainuma, Rikiya Kobashi, Keisuke Shinomiya, Takuo Nishida</i> <i>LINTEC Corporation</i>	06-02 Evaluation of Transmission Line Properties on Si-CMOS chip by Probe Backside Reflection Method in Millimeter-Wave Frequencies <i>Ryo Sakamaki¹, Seitaro Kon¹, Ichiro Somada², Takeshi Yoshida³, Shuhei Amakawa³, Minoru Fujishima³</i> <i>1) AIST</i> <i>2) Mitsubishi Electric Corporation</i> <i>3) Hiroshima University</i>
16:30	04-03 Quantum co-packaged optical assembly <i>Bernard Lee¹, Yang Chen¹, R.Ryan Vallance¹, Michael O'Farrell¹, Abu Bakar Bhatti¹, Richard Pitwon²</i> <i>1) Senko Advanced Components</i> <i>2) Resolute Photonics</i>	05-03 Study on the Novel Fabrication Procedure of Polyimide Multilayer Circuits for a Space Transformer of DRAM Probe Card using Parallel Build-up Process <i>Seong-Dae Park, Hyunseung Yang, Hyeok Jang</i> <i>Korea Electronics Technology Institute</i>	06-03 Socket Design for 1x4 mmWave AiP with Beamforming Testing <i>Chia-Ching Chu, Hong-Sheng Huang, Wen-Chun Hsiao, Sheng-Chi Hsieh, Chen-Chao Wang</i> <i>ASE, Inc.</i>
16:55	04-04 Development of Re-assemblable Multifiber Connector for Co-Packaged Optics <i>Alexander William Setiawan Putra, Kentaro Matsuda, Motohito Takezaki</i> <i>Hakusan Inc.</i>	05-04 A Novel of Ultra Thinner Thermoelectric Device for Wireless Sensor Application <i>Takuro Yoneda¹, Kosuke Watanabe², Koji Miyazaki², Kunihsa Kato¹</i> <i>1) Lintec Corporation</i> <i>2) Kyushu University</i>	06-04 High Reliability Solutions of EMI Shielding Technology for Advanced SiP Module <i>Mike Tsai, Ryan Chiu, James Lin, Ming-fan Tsai, Eddie Zheng, Dave Chen, Tim Chang, Nicholas Kao, J.Y. Chen, Yu-Po Wang</i> <i>SPIL</i>
17:20	Interview with the Authors (Discussion after the session) + Sponsor's Exhibition		
17:35-18:15	Special Speech I Hall I Chairperson Takaaki Ishigure (Keio University) and Hideyuki Nawata (Nissan Chemical Corporation)		
17:35	Wafer-scale packaging of photonic switches and transceivers Geert Van Steenberge (imec and Ghent University)		S-05
19:15	Welcome Reception		
21:15	Close		

November 14, 2024 (Thursday)

4F/5F Main Hall I		1F Room I	1F Room II
9:00	Registration		
9:20-11:00	Plenary Speech III Hall I Chairperson Shoji Uegaki (Crane Research) and Taiji Sakai (TSMC Japan 3DIC R&D Center, Inc.)		
9:20	Plenary Speech III : Advance Heterogeneous Integration package solution for Silicon Photonics application Scott Chen (Advanced Semiconductor Engineering, Inc.)		
9:20-11:00	Plenary Speech IV Hall I TBD		
10:10	Plenary Speech IV : TBD John Knickerbocker (IBM)		
11:00	Coffee break + Sponsor's Exhibition		
11:10-12:40	Session 7: Advanced PKG I Chairperson Taiji Sakai (TSMC Japan 3DIC R&D Center, Inc.) Chinami Marushima (IBM Japan, Ltd.)	Session 8: Process and Material Technologies III Chairperson Shinya Takyu (LINTEC Corporation) Naoko Araki (DAICEL CORPORATION)	Session 9: Bio electronics I Chairperson Beomjoon Kim (University of Tokyo) Takafumi Fukushima (Tohoku University)
11:10	(Invited) TBD Hiroaki Kasai Hitachi High-Tech Corporation	(Invited) Polymer Optical Waveguide for Silicone Photonics Nobuyuki Ootzawa AGC Inc.	(Invited) Wearable Electronic Packaging Technology for VR and Biomedical Applications Seiichi Takamatsu The University of Tokyo
11:35	Low temperature bonding process for Bi2Te3/Si heterojunctions Kaixuan Wang Kaixuan Wang Southeast University	New PFAS-free optical adhesive with high heat resistance and low refractive index Masashi Kajiwara, Yoshito Yamada, Takashi Yamaguchi, Noriyuki Sakai NAMICS Corporation	(Invited) Wood Nanocellulose-Based Green Electronics Hiroataka Koga Osaka University
12:00	Oxide microtubes fabrication with 10µm to 5µm pitches and assembly characterization Natacha Raphoz, Olivier Maillart, Patrick Peray, Cloe Desbordes, Frederic Berger, Alain Gueugnot CEA-LETI	Verification of dicing method for Silicon Photonic wafers Haruki Otaka, Kazuhiro Yoshida, Tomoharu Fujii Shinko Electric Industries Co., Ltd.	Failure of PCBs Used as Edge-Card Connectors for Surgical Endoscopes Kshitij Jayantilal Bopalkar, Viraj Patwardhan, Anthony Okello, Adi Chola Venkatesh Vision Engineering Intuitive
12:25	Interview with the Authors (Discussion after the session) + Sponsor's Exhibition		
12:40-13:45	Lunch (free time)		
13:45-15:40	Session 10: Hybrid bonding Chairperson Takafumi Fukushima (Tohoku University) Kenji Takahashi (AIST)	Session 11: Photonics II (Photonics Packaging) Chairperson Hidetoshi Numata (IBM Research - Tokyo) Nobuo Ohata (Mitsubishi Electric Corporation)	Session 12: Bio electronics II Chairperson Shigenori Aoki (LINTEC Corporation) Kai Takeuchi (Tohoku University)
13:45	(Invited) Hybrid Bonding in Advanced Heterogenous Integration: Key Metrology Enablers Bongsu Lee Adeia Inc.	Ultra High Optical Output Power 8-channel ELS Module Employing a Blind Mate Optical Connector for Co-Packaged Optics Yuki Shiroishi, Taketsugu Sawamura, Kohei Umeta, Hideyuki Nasu Furukawa Electric Co., Ltd	Diagnosing PCB(A) deficiencies in medical instruments during reprocessing and sterilization cycles Toshak Singhal, Viraj Patwardhan Intuitive Surgical Inc
14:10	(Invited) Fine pitch die-to-wafer hybrid bonding integration Ye Lin imec	High-Bandwidth Optical Transmission with Single External Laser Source (ELS) and Polymer Splitters for Co-packaged Optics Satoshi Suda, Md Omar Faruk Rasel, Takayuki Kurosu, Akihiro Noriki, Tadashi Muraio, Takeru Amano AIST	Development of optical microneedle lens array to deliver light efficiently for photodynamic therapy to treat basal cell carcinoma Anthony Lefebvre¹, Wataru Hanamoto¹, Jongho Park¹, Anne-Sophie Dewalle-Vignion², Guillaume Paul Grolez², Nadira Delhem², Laurent Mortier², Beomjoon Kim¹ 1) The University of Tokyo 2) Univ. Lille
14:35	(Invited) Next-Generation Wafer-to-Wafer Bonding Technologies for Sub-50nm Bonding Overlay Accuracy Tomohiro Chiba Nikon Corporation	Co-Design of Photonic IC, Electronic IC, and Interposer for 1.6 Tbps O/E Converter in Active Optical Package Naoki Matsui¹, Akihiro Noriki², Haruhiko Kuwatsuka², Fumi Nakamura², Satoshi Suda², Takayuki Kurosu², Takeru Amano², Satoshi Ishikawa¹, Hiromichi Yoshikawa¹, Dan Maeda¹, Tomoya Sugita¹, Hiroataka Uemura¹ 1) KYOCERA Corporation 2) AIST	Simulation and Fabrication of Highly Bendable Advanced 3D Corrugated Interconnects Using Flexible FOWLP HAN ZHANG, Jiayi Shen, Chang Liu, Tetsu Tanaka, Takafumi Fukushima Tohoku University
15:00	(Invited) CMOS Directly Bonded to Array (CBA) Technology for Future 3D Flash Memory Masayoshi Tagami Kioxia Corporation	(Invited) TBD	Multichip-to-Wafer Mini-LED Bonding Technology for Photobiomodulation Sheet Devices Using Flexible FOWLP Xingyao Guo, Jiayi Shen, Chang Liu, Tetsu Tanaka, Takafumi Fukushima Tohoku University
15:25	Interview with the Authors (Discussion after the session) + Sponsor's Exhibition		
15:40	Coffee break + Sponsor's Exhibition		
15:50-16:30	IEEE EPS Special Speech I Hall I Chairperson Shinya Takyu (LINTEC Corporation) and Eiji Higurashi (Tohoku University)		
15:50	IEEE EPS Special Speech I: Technologies for Chiplet based System Integration Tanja Braun (Fraunhofer IZM)		
16:30-16:50	IEEE EPS Special Speech II Hall I Chairperson Shinya Takyu (LINTEC Corporation) and Eiji Higurashi (Tohoku University)		
16:30	IEEE EPS Special Speech II: Mechanical Behavior of Solder Micro Bumps in Advanced Packaging for Heterogeneous Integration Jeffrey Suhling (Auburn University)		
16:50	Coffee break + Sponsor's Exhibition		
17:00-18:00	Early Career Researcher's (ECR) Session (Open Forum with Beer) @ 1F Room I Chairperson TBD Poster presentation		
	Multi-channel Integration of Polymer Spot Size Expander on Silicon Photonics Chip Atsuki Sawada¹, Yoshiki Kamiura², Chiemi Fujikawa¹, Osamu Mikami³ 1) Tokai University, 2) Kyushu University 3) Universiti Teknologi Malaysia	Formation of Au hollow micro-bump arrays for low temperature Au-Au bonding Shintaro Goto¹, Kai Takeuchi¹, Le Hac Huong Thu², Takashi Matsumae², Hideki Takagi², Yuichi Kurashima², Eiji Higurashi¹ 1) Tohoku University 2) AIST	Development of Through Semiconductor Via manufacturing process for heterogeneous integration of GaN power device on Si-LSI Hidejiro Mishima, Kaiyuan Zheng, Satoshi Matsumoto, Satoko Shinkai Kyushu Institute of Technology
	Direct Connection of Multimode Polymer Waveguide and Multimode Fibers Using the Mosquito Method Tatsuya Nakamura, Takaaki Ishigure Keio University	Structural investigation of microchannel and optical waveguide co-integrated sensor devices Tomohiro Ichizuka, Takaaki Ishigure Keio University	Field size converter for edge coupling of multimode LD to thin film waveguide Yuya Yamanishi¹, Junichi Inoue¹, Keisuke Ozawa¹, Kenji Kintaka², Kouki Ichihashi², Ura Shogo¹ 1) Kyoto Institute of Technology 2) National Institute of Advanced Industrial Science and Technology 3) Panasonic Holdings Corp.
	Feasibility Study of Self Assembly Using Copper Nano Film Formed by Blue Laser for Die-to-Wafer Hybrid Bonding Hayami Asahara, Kiyokazu Yasuda Osaka University	3D Polymer Optical Waveguide-based Fan-in/out Device for Silicon Photonics Anzu Ito, Takaaki Ishigure Keio University	Fixed connection of single-mode polymer optical waveguide with single-mode optical fiber Shunsuke Tashida, Takaaki Ishigure Keio University
	Sequential surface treatment process with VUV light and Ar plasma for room temperature Au-Au bonding Mika Ogino, Kai Takeuchi, Eiji Higurashi Tohoku University	Adhesion between Si Substrates in Liquid Water using Inorganic Polymer Daiki Nemoto, Kai Takeuchi, Eiji Higurashi Tohoku University	
18:00	Close		

November 15, 2024 (Friday)

4F/5F Main Hall I		1F Room I	1F Room II
9:00		Registration	
9:20		ECR Award Ceremony	
9:30-10:10	Special Speech II Hall I Chairperson TBD		
9:30	Special Speech II: Innovation and steps in hetero-integration Harald Kuhn (Fraunhofer ENAS)		S-03
10:10-10:50	Special Speech III Hall I Chairperson Kraisorn Throngnumchai (Kanagawa Institute of Technology) and Yutaka Uematsu (Hitachi, Ltd.)		
10:10	Special Speech III: Wireless Power Transfer Theory Established Last Decade Takashi Ohira (Toyohashi University of Technology)		S-04
10:50	Coffee break + Sponsor's Exhibition		
11:00-12:55	Session 13: IEEE EPS Technical session Chairperson Shigenori Aoki (LINTEC Corporation) Takashi Hisada (Rapidus)	Session 14: Advanced Automotive Electronics Chairperson Atsushi Nakamura (Ultimate Technologies Inc.) Yutaka Uematsu (Hitachi, Ltd.)	Session 15: Advanced PKG II Chairperson Kiyokazu Yasuda (Osaka University) Shoji Uegaki (Crane Research)
11:00	(Invited) TBD Mohan Kathaperumal Georgia Institute of Technology	13-01 (Invited) Application of EMC Simulation Including Semiconductor to Reduce Development Lead Time Kazuki Furukawa AISIN Corporation	14-01 Novel Additive Manufacturing Platform for Freeform 3D Microelectronics and Packaging Darragh Walsh, Jeroen Sol, Hylke Akkerman Holst Centre/TNO
11:25	(Invited) TBD Yoichiro Sato AGC Inc.	13-02 Compact Design for Automotive High-Performance Computing Using a Two-Layer Daughter Board Structure Soshi Shimomura, Masako Kato, Yutaka Uematsu Hitachi, Ltd.	14-02 Effect of Microstructure on the Electromigration Performance of 2-µm-Cu Redistribution Line under In-situ SEM Observation Min-Yan Tsai, Ting-Chun Lin, Yen-Cheng Huang, Shan-Bo Wang, Yung-Sheng Lin, Kwang-Lung Lin ASE Group
11:50	(Invited) TBD SB Park Binghamton University	13-03 Efficient German License Plate Recognition System Integrating YOLOv8 Model and EasyOCR Hasan Aljzaere, Atul Chandra Nath, Wolfram Hardt Chemnitz University of Technology	14-03 Implementation of Curved CMOS Image Sensors by Transferring Silicon-On-Insulator Layers Masahide Goto, Shigeyuki Imura, Hiroto Sato NHK Science & Technology Research Laboratories
12:15	(Invited) TBD	13-04 High-Performance Flip-Chip BGA Packages Reliability Prediction in Automotive Applications Bo-Heng Chen, Wei-Hong Lai, Chin-Li Kao, Alexcc Wang, CP Hung ASE Inc.	14-04
12:40	Interview with the Authors (Discussion after the session) + Sponsor's Exhibition		
12:55-14:25	Lunch (free time)		
14:25-16:45	Session 16: Photonics IV (Glass and Polymer for Photonics) Chairperson Hideyuki Nasu (Furukawa Electric Co., Ltd.) Motohito Takezaki (Hakusan Inc.)	Session 17: Automotive Power Electronics Chairperson Yutaka Uematsu (Hitachi, Ltd.) Atsushi Nakamura (Ultimate Technologies Inc.)	Session 19: Power Electronics Materials and devices of UWBG and WBG semiconductors Chairperson Kentaro Kaneko (Ritsumeikan University) Hiroki Imabayashi (University of Fukui)
14:25	(Invited) TBD	16-01 (Invited) EMC overview, Causes and Physics Hideho Yamamura Ultimate Technologies Inc.	17-01 (Invited) Recent progress and task of GaN materials and devices for power applications Yohei Otoki SCIOCS Co. Ltd.
14:50	Towards scalable aligned two photon lithography for photonic integration Mareike Trappen, Matthias Blaicher, Tobias Hoose, Nicole Lindenmann, Stephan Dottermusch, Benjamin Richter, Andrea Bertoncini, Michael Thiel Nanoscribe GmbH & Co. KG	16-02 A Review of BMW iX3 Power Module – Part 1: Inner Configuration, Die Attachment, Busbar Connection and Molding Thiyu Warnakulasooriya, Jiyeon Choi, Sihoon Choi, Jun Imaoka, Masayoshi Yamamoto Nagoya University	17-02 Ag Sintering based Die Attach for Power Package and Power Module Applications Tamimoto Hideaki Tamimoto Hideaki, Kazuki Matsumura, Kazuyuki Nakagawa, Kenji Ikura, Chikara Obama Renesas Electronics Corporation
15:15	Loss reduction of Y-branched single-mode polymer optical waveguide for MUX/DEMUX devices in mode division multiplexing links. Sei-ya Sakai, Takaaki Ishigure Keio University	16-03 A Review of BMW iX3 Power Module – Part 2: Novel Heatsink Structure, Stacked-plate Fin Configuration Jiyeon Choi, Thiyu Warnakulasooriya, Sihoon Choi, Jun Imaoka, Masayoshi Yamamoto Nagoya University	17-03 Simulation Study of Factor Effect on Transient Thermal Ramp Up Test Performance for Electronic Power Devices Nick Chenchao Zhong, Haibo Fan, Yuning Shi Nexperia Group
15:40	Polarization dependent characteristics of polymer optical waveguide Takumi Wakabayashi, Takaaki Ishigure Keio University	16-04 Session 18: Photonics V (Laser Technology for photonics) Chairperson Hideyuki Nawata (Nissan Chemical Corporation) Junichi Inoue (Kyoto Institute of Technology)	19-04 Effect of Sb dopant in r-GeO2 thin films for high-temperature growth Toya Yagura ^{1,2} , Yuri Shimizu ² , Toyosuke Ibi ¹ , Isao Takahashi ¹ , Kentaro Kaneko ^{1,2} 1) Patentix Inc. 2) Ritsumeikan Univ.
16:05	Fabrication of a glass sub-mount with high heat dissipation Takuma Fujita, Asami Uchiyama, Shinya Okuda, Mizuki Shirao, Nobuo Ohata Mitsubishi Electric Corporation	16-05 Heat Assisted Magnetic Recording - Ultra-dense laser and plasmonic component integration to increase storage density on magnetic media Mark Gubbins, Beverley McConnell, Michael Kautzy, Anil Reddy, Richard Pitwon Seagate Technology	18-02 Interview with the Authors (Discussion after the session) + Sponsor's Exhibition
16:30	Interview with the Authors (Discussion after the session) + Sponsor's Exhibition		
16:45	Close		